# **BGA Heat Sink - High Performance** maxiFLOW w/Thermal Tape





ATS Part#: **ATS-52310P-C1-R0** 

Description: 31.00 x 31.00 x 17.50 mm BGA Heat Sink - High Performance maxiFLOW w/Thermal

Tape

Heat Sink Type: maxiFLOW
Heat Sink Attachment: Thermal Tape

Equivalent Part Number: ATS-52310P-C2-R0

\*Image above is for illustration purpose only.

#### **Features & Benefits**

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- · Fabricated from extruded aluminum, which minimizes thermal resistance from the base to the fins, reduces weight and keeps costs low
- · Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks

### **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.3 °C/W	2.7 °C/W	2.3 °C/W	2.1 °C/W	1.9 °C/W	1.8 °C/W	1.7 °C/W
	Ducted Flow	2.7	N/A	N/A	N/A	N/A	N/A	N/A

### **Product Detail**

	31.00 mm					Finish
	01.00 11111	31.00 mm	17.50 mm	54.94 mm	T412	BLUE-ANODIZED
*Image above is for illustration purpose only.	<ul> <li>Dimension</li> <li>ATS-52310</li> <li>(Saint-Gob</li> <li>Thermal postpolication</li> <li>ATS reserve performance</li> <li>ATS certification</li> </ul>	oP-C2-R0 is the example of the case of the	emponent size.  The provided for reference are or change its provided k assembly is RoHS.  The provided for reference are or change its provided k assembly is RoHS.	ly with an equivalent nce only. Actual perfo ducts without notice -6 and REACH comp	t thermal ormance	interface material may vary by



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